Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	128	\$3mount and (light adj emitting adj diode or LED) and metal\$3 and plate and bond\$3 and (therm\$4 near5 conduct\$5) and \$5conduct\$5 and fill\$3 and insulat\$3 and (heat same transfer\$3) and (recess or groove or protrusion) and (layer or film) and (embedd\$3 or bury\$3 or imbed\$4 or implant\$5 or inlay\$3) and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 17:57
S16	399	\$3mount\$3 and (light adj emitting adj diode or LED) and metal\$3 and plat\$3 and bond\$3 and (therm\$4 same conduct\$5 or therm\$4 same contact) and \$5conduct\$5 and fill\$3 and (heat same (transfer\$3 or spread\$3 or dissipat\$3)) and (recess\$3 or groov\$2 or protru\$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd\$3 or bury\$3 or imbed\$4 or implant\$5 or inlay\$3 or deposit\$3) and die and wir\$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:57
S17	. 25	(438/22-47.ccls. or 257/79-103, 676,774.ccls.) and \$3mount\$3 and (light adj emitting adj diode or LED) and metal\$3 and plat\$3 and bond\$3 and (therm\$4 same conduct\$5 or therm\$4 same contact) and \$5conduct\$5 and fill\$3 and (heat same (transfer\$3 or spread\$3 or dissipat\$3)) and (recess\$3 or groov\$2 or protru\$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd\$3 or bury\$3 or imbed\$4 or implant\$5 or inlay\$3 or deposit\$3) and die and wir\$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:58

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S18		\$13 and \$3mount\$3 and (light adjemitting adj diode or LED) and metal\$3 and plat\$3 and bond\$3 and (therm\$4 same conduct\$5 or therm\$4 same contact) and \$5conduct\$5 and fill\$3 and (heat same (transfer\$3 or spread\$3 or dissipat\$3)) and (recess\$3 or groov\$2 or protru\$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd\$3 or bury\$3 or imbed\$4 or implant\$5 or inlay\$3 or deposit\$3) and die and wir\$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/07/15 19:39
S19	67	S14 or S15 or S17 or S18	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:00
S20	29	(438/22-47.ccls. or 257/79-103, 676,774.ccls. or 361/794,813,414. ccls. or 362/294,241,555.ccls.) and \$3mount\$3 and (light adj emitting adj diode or LED) and metal\$3 and plat\$3 and bond\$3 and (therm\$4 same conduct\$5 or therm\$4 same contact) and \$5conduct\$5 and fill\$3 and (heat same (transfer\$3 or spread\$3 or dissipat\$3)) and (recess\$3 or groov\$2 or protru\$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd\$3 or bury\$3 or imbed\$4 or implant\$5 or inlay\$3 or deposit\$3) and die and wir\$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OŅ	2007/07/15 19:52

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521		(US-20040012958-\$ or US-20020085390-\$ or US-20020004251-\$ or US-20030170922-\$ or US-20030022407-\$ or US-20010052600-\$ or US-20010050370-\$ or US-20060119250-\$ or US-20050072981-\$ or US-20050072981-\$ or US-20030189830-\$).did. or (US-6936855-\$ or US-6498355-\$ or US-6943433-\$ or US-6828170-\$ or US-6885563-\$ or US-6828170-\$ or US-6335548-\$ or US-6311060-\$ or US-6756610-\$ or US-6558970-\$, or US-6534330-\$ or US-6318886-\$ or US-6784530-\$ or US-6706546-\$).did.	US-PGPUB; USPAT	OR	ON	2007/07/15 19:23
S64	387	\$3mount\$3 and (light adj emitting adj diode or LED) and metal\$3 and plat\$3 and bond\$3 and (therm\$4 same conduct\$5) and \$5conduct\$5 and fill\$3 and (heat same (transfer\$3 or spread\$3 or dissipat\$3)) and (recess\$3 or groov\$2 or protru\$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd\$3 or bury\$3 or imbed\$4 or implant\$5 or inlay\$3 or deposit\$3) and die and wir\$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 13:05
S65	125	(438/22-47.ccls. or 257/79-103, 676,720,774,783.ccls. or 361/386, 414,793,813.ccls. or 362/241,294, 555.ccls.) and \$3mount\$3 and metal\$3 and plat\$3 and bond\$3 and (therm\$4 same conduct\$5 or therm\$4 same contact) and \$5conduct\$5 and fill\$3 and (heat same (transfer\$3 or spread\$3 or dissipat\$3)) and (recess\$3 or groov\$2 or protru\$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd\$3 or bury\$3 or imbed\$4 or implant\$5 or inlay\$3 or deposit\$3) and die and wir\$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 13:14

S66	107	(438/22-47.ccls. or 257/79-103, 676,720,774,783.ccls. or 361/386, 414,793,813.ccls. or 362/241,294, 555.ccls.) and \$3mount\$3 and metal\$3 and plat\$3 and bond\$3 and (therm\$4 same conduct\$5) and \$5conduct\$5 and fill\$3 and (heat same (transfer\$3 or spread\$3 or dissipat\$3)) and (recess\$3 or groov\$2 or protru\$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd\$3 or bury\$3 or imbed\$4 or implant\$5 or inlay\$3 or deposit\$3) and die and wir\$5 and (layer or film) and	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/07/17 13:26
S67	30	@ad<"20030526" S66 and (light adj emitting adj diode or LED)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 13:24